DATE: 11 JUL 91

				22.1 MOMENCENTRIES DE	ASS'Y P/N: 31140E391 SHEET:
FMEA REF.	fMEA REV.	NAME OTY & DRAWING REF. DESIGNATION  MCIU-D&C DATA INTERFACE OTY-1 SCHEMATIC ED 87305	FAILURE MODE AND CAUSE  MODE: CORRUPT DATA SENT TO D&C.  CAUSE(S): (1) INPUT SHIFT REGISTER OR LATCH MALFUNCTION FOR DATA	FAJLURE EFFECT ON END ITEM  LOSS OF COMMUNICATION WITH D&C INTERFACE WILL INITIATE D&C COMMUNICATION FAILURE DETECTION, AUTOBRAKES, ARM-COMES TO REST, GPC GOES	HDWR / FUNC. RATIONALE FOR ACCEPTANCE 2/1R CRITICALITY SCREENS: A-PASS, B-PASS, C-PASS  DESIGN FEATURES  PROCESSING OF THE CLOCK AND OF THE SIROBE SIGNAL, 1S PERFORMED BY THREE ACTIVE EEE PARTS. EACH SIGNAL IS BUFFERED BY A COMPLEMENTARY TRANSISTOR PAIR (2H2Z2ZA AHD ZH2907A) AND SHAPED BY A CMOS SCHMIDT IRIGGER GATE (4093).  CMOS DEVICES OPERATE AT LOW POWER AND HENCE DO NOT EXPERIENCE SIGNIFICANT OPERATING SIRESSES. THE TECHNOLOGY IS MATURE AND
-			ONLY.	INTO IDLE MODE. LOSS OF COMPUTER SUPPORTED MCDES. ABE COMMUNICATION PATH REMAINS OPERABLE. LOSS OF LIMPING DURING END EFFECTOR CAPTURE.  WORST CASE  UNABLE TO RELEASE BRAKES.	DEVICE RELIABILITY HISTORY IS WELL DOCUMENTED. ALL STRESSES ARE ADDITIONALLY REDUCED BY DERAITING THE APPROPRIATE PARAMETERS IN ACCORDANCE WITH SPAR-RMS-PA.003. SPECIAL HANDLING PRECAUTIONS ARE USED AT ALL STAGES OF MANUFACTURE TO PRECLUDE DAMAGE/STRESS DUE TO ELECTROSTATIC DISCHARGE.  DISCRETE SEMICONDUCTOR DEVICES SPECIFIED TO AT LEAST THE TX LEVEL OF MIL S-19500. ALL DEVICES ARE SUBJECTED TO RE-SCREENING BY AN INDEPENDANT TEST HOUSE. SAMPLES OF ALL PROCURED LOTS/DATE CODES ARE SUBJECTED TO DESTRUCTIVE PHYSICAL ANALYSIS (OPA) TO VERIFY THE INTEGRITY OF THE MANUFACTURING PROCESSES. DEVICE STRESS LEVELS ARE, DERAIED IN ACCORDANCE WITH SPAR-RMS-PA.003 AND VERFFIED BY DESIGN REVIEW.  EEE PARTS HAVE BEEN SELECTED AND CONTROLLED IN ACCORDANCE WITH SPAR-RMS-PA.003. THIS DOCUMENT DEFINES THE PROGRAM REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH SPAR-RMS-PA.003. THIS DOCUMENT DEFINES THE PROGRAM REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH SPAR-RMS-PA.003. THIS SOCUMENT DEFINES THE PROGRAM REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH SPAR-RMS-PA.003. THIS SOCUMENT DEFINES THE PROGRAM REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH SPAR-RMS-PA.003. THIS SOCUMENT DEFINES THE PROGRAM REQUIREMENTS FOR MONITORING AND CONTROLLED IN ACCORDANCE WITH SPAR-RMS-PA.003. THIS SOCUMENT DEFINES THE PROGRAM REQUIREMENTS FOR MONITORING AND CONTROLLED TO AT LEAST "ESTABLISHED
				LOSS OF ARM ORIVE CAPABILITY.  REDUNDANT PATHS REMAINING TO CONTINUE OPERATIONS: 1) DIRECT DRIVE 2) BACK-UP ORIVE 3) JETTISON (TO SECURE ORBITER)	RELIABILITY LEVELS, AND ADEQUATE DERATING OF PART STRESS LEVELS. PROCEDURES AND ACTIVITIES ARE SPECIFIED TO ENSURE AT LEAST EQUIVALENT QUALITY FOR MONSTANDARD AND IRREGULAR PARTS. RELIABILITY ANALYSIS HAS CONFIRHED NO PARTS WITH GENERICALLY HIGH FAILURE RATES. AEROSPACE DESIGN STANDARDS FOR DETAILING ELECTRONIC PARTS PACKAGING, MOUNTING AND STRUCTURAL/MECHANICAL/INTEGRITY OF ASSEMBLIES ARE APPLIED. SUCH DESIGN HAS BEEN REVIEWED AND FOUND SATISFACTORY THROUGH THE DESIGN AUDIT PROCESS, INCLUDING THE USE OF RELIABILITY, MAINTAINABILITY AND SAFETY CHECKLISTS. MATERIAL SELECTION AND USAGE CONFORMS TO SPAR-SG. 368 WHICH IS EQUIVALENT TO THE NASA MATERIALS USAGE REQUIREMENTS. WORST CASE ANALYSIS HAS BEEN CONDUCTED TO ENSURE THAT PERFORMANCE CAN BE MET UNDERS WORST CASE TEMPERATURE AND AGING EFFECTS. EEE PARTS STRESS ANALYSIS HAS BEEN COMPLETED AND CONFIRMS THAT THE PARTS MEET THE DERATING REQUIREMENTS.
				SECURE UNGITERY	PRINTED CIRCUIT BOARD DESIGNS HAVE BEEN REVIEWED TO ENSURE ADEQUATE CERCUIT PATH WIDTH AND SEPARATION AND TO CONFIRM APPROPRIATE DIMENSIONS OF CIRCUIT SOLDER PADS AND OF COMPONENT HOLE PROVISIONS.  PARTS MOUNTING METHODS ARE CONTROLLED IN ACCORDANCE WITH MSFC-STD-136 AND CAE PD93489. THESE DOCUMENTS REQUIRE APPROVED-MOUNTING METHODS, STRESS RELIEF, AND COMPONENT SECURITY.  WHERE APPLICABLE, DESIGN DRAWINGS AND DOCUMENTATION GIVE CLEAR IDENTIFICATION OF HANDLING PRECAUTIONS FOR ESD SENSITIVE

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PRO.	JECT: SRMS (-5 MC Y NOMENCLATURE: DI	U INSTALLED)	SYSTEM: D&C SUBSYSTEM ASS'Y P/N: 51140E391	SHEE1:
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FMEA REF.	FMEA REV,	NAME, QTY, & DRAWING REF. DESIGNATION	FAILURE MODE AND CAUSE	FAILURE EFFECT ON END ITEM	HDWR / FUNC. RATIONALE FOR ACCEPTANCE 2/1R CRITICALITY SCREENS A PAGE B.DAGE C.DAGE
PREPARED BY:	O	MCIU-D&C DATA INTERFACE GTY-1 SCHEMATIC ED B7305	MODE: CORRUPT DATA SENT TO D&C.  CAUSE(S): (1) INPUT SHIFT REGISTER OR LATCH MALFUNCTION FOR DATA ONLY.	LOSS OF COMMUNICATION WITH DAC INTERFACE WILL INITIATE DBC COMMUNICATION FAILURE DETECTION. AUTOBRAKES. ARM COMES TO REST. GPC GOES INTO IDLE MODE. LOSS OF COMPUTER SUPPORTED MODES. ABE COMMUNICATION PATH REMAINS OPERABLE. LOSS OF LIMPING DURING END EFFECTOR CAPTURE. WORST CASE UNABLE TO RELEASE BRAKES. LOSS OF ARM DRIVE CAPABILITY.  REDUNDANT PATHS REMAINING TO CONTINUE OPERATIONS: 1) DIRECT DRIVE 2) BACK-UP DRIVE 3) JETTISON (TO SECURE ORBITER)	BOARD ASSEMBLY DRAWINGS INCLODE THE REQUIREMENT FOR SOLDERING STANDARDS IN ACCORDANCE WITH NHB 5300.4(3A) AND JSC 08800A.  PHE CIRCUIT IS PACKAGED ON A PAIR OF BOARDS MECHANICALLY JOINED BY NACHINED SPACES, ALONG TOVE BOOKS TO FORM A MODULE I THE MODULE IS SUPPORTED IN MACHINED CUIDEMAYS IN THE ELECTRONICS PACKAGE. LATERAL RESTRAINT IS PROVIDED BY THO PAIRS OF BOW SPRINGS REGIONAL RESTRAINTS PROVIDED BY THO PAIRS OF BOW SPRINGS REGIONAL THE CUIDEMAYS. THE LOWER EOGE OF EACH BOARD INTERFACES VIA RESTRAINED BITCH ELECTRONICS ON THE UPPER EDGE OF THE MODULE IS RESTRAINED BY THE ELECTRONICS ON THE UPPER EDGE OF THE MODULE IS RESTRAINED BY THE ELECTRONICS ON THE UPPER EDGE OF THE MODULE IS RESTRAINED BY THE PROPERTY OF THE PERFORMANCE.  PHYDROMACHIONS BETWEEN THE DAC INTERFACE CONNECTORS AND ALL MCTULE PRINTED BOARD CONNECTORS IS ACHIEVED BY HEAMS OF FILM-MIRING, INTS IS STITLAR TO A FIRST BY THE DIRECTION OF THE PERFORMANCE.  HYTERCONNECTIONS BETWEEN THE DAC INTERFACE CONNECTORS AND ALL MCTULE PRINTED CIRCUIT AND HAS KAPTON INSULATION. THE FILM MIRITED PRINTED CIRCUIT AND HAS KAPTON INSULATION. THE FILM MIRITED PRINTED CIRCUIT AND HAS KAPTON INSULATION. THE FILM MIRITED PRINTED CIRCUIT AND HAS KAPTON INSULATION. THE FILM MIRITED PRINTED CIRCUIT SHAPE OF THE CIRCUITS PACKAGE, THE ELECTRONICS TRAY, AND ALL PCB SOCKET CONNECTORS ARE SUPPLIED AS A KIT. THE FILM WIR IN GIVE SIS. ALL OBELIVERED ASSEMBLES ARE SUBJECTED TO ACCEPTANCE TESTING HILL INCLUDES: AVIA AND ALL MIRITED CONTINUOUS AUTOMATIC CONTINUITY. SCAN OF ALL CONTACTS, INSULATION RESISTANCE, AND DIELECTRIC TISTING HILL MIRITED TO THE FILM WIR IN GIVE SISS. ALL OBELIVERED TO SETSING OF THE FORMED WIR INSULATION RESISTANCE (SOD VOIC), AND CONTINUITY.  SIRBIGIN.  INSULATION RESISTANCE (SOD VOIC), AND CONTINUITY.  INE TEST PROGRAM FOR THE DECIRCUITS PACKAGE AND ACCEPTANCE TESTING OF THE FULLY ASSEMBLED ELECTRONICS PACKAGE AND ACCEPTANCE TESTING OF THE FULLY ASSEMBLED ELECTRONICS PACKAGE AND ACCEPTANCE TESTING OF THE FULLY ASSEMBLED ELECTRONICS PACKAGE AND ACCEPTANC
					DATE: 11 JUL 91 CIL REV: D

PROJECT: SRMS (-5 MCIU INSTALLED)
ASS'Y NOMENCLATURE: DEC PAREL

SYSTEM: D&C SUBSYSTEM ASS'Y P/R: 51140E391	SHEE1:
RATIONALE FOR ACCEPTANCE	

FMEA FMEA NAME GIY. REF. REV. DRAVING REF	FAILURE MODE FAILURE EFFECT	100.00 4 50.000
DESIGNATION		HDWR / FUNC. RATIONALE FOR ACCEPTANCE 2/1R CRITICALITY SCREENS: A-PASS, B-PASS, C-PASS
1045 B MCIU-DEC DAIA INTERFACE GTY-1 SCHEMATIC ED 87305	MODE: CORRUPT DATA SENT TO D&C.  CAUSE(S): (1) INPUT SHIFT REGISTER OR LATCH MALFUNCTION FOR DATA ONLY.  COMMUNICATION AUTOBRAKES. AND COMES TO REST. GPC GOES INTO IDLE MODE. LOSS OF COMPUTER SUPPORTED MODES. ABE COMMUNICATION PATH REMAINS OPERABLE. LOSS OF LIMPING DURING END EFFECTOR CAPTURE.  WORST CASE  UNABLE TO RELEASE BRAKES. LOSS OF ARM DRIVE CAPABILITY.  REDUNDANT PATHS REMAINING  TO CONTINUE OPERATIONS: 1) DIRECT DRIVE 2) BACK-UP DRIVE 3) JETTISON (10 SECURE ORBITER)	ACCEPTANCE TESTS  THE MARDWARE TIEM IS SUBJECTED TO THE FOLLOWING ACCEPTANCE ENVIRONMENTAL TESTING AS PART OF THE D&C PANEL.  O VIBRATION: LEVEL AND DURATION - REFERENCE TABLE TO THE PART OF THE PAR

SO40237A ATTACHMENT -PAGE 50 OF 47:

PREPARED BY:

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PROJECT:	SRMS	(-5	MCIU	INSTAL	EO)
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SYSTEM: D&C SUBSYSTEM ASS'Y P/N: 51140E391

DATE: 11 JUL 91

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FHEA REF.	FHEA REV.	NAME, OTY & DRAWING REF. DESIGNATION	FATLURE MODE AND CAUSE	FAILURE EFFECT ON END 11EM	HDWR / FUNC. RATIONALE FOR ACCEPTANCE 2/IR CRETICALETY SCREENS: A-PASS, B-PASS, C-PASS
1045	0	MCIU-D&C DATA INTERFACE GIY-1 SCHEMATIC ED 87305	MODE: CORRUPT DATA SENT TO D&C.  CAUSE(S): (1) INPUT SHIFT REGISTER OR LATEN HALFUNCTION FOR DATA ONLY.	LOSS OF COMMUNICATION WITH D&C INTERFACE WILL INTERFACE WILL INTERFACE WILL INTITATE D&C COMMUNICATION FAILURE DEFECTIOM. AUTOBRAKES. ARM COMES TO REST. GPC GOES INTO 10LE MODE. LOSS OF COMPUTER SUPPORTED HODES. ABE COMMUNICATION PATH REMAINS OPERABLE. LOSS OF LIMPING DURING END EFFECTOR CAPTURE.  WORST CASE  UNABLE TO RELEASE BRAKES. LOSS OF ARM DRIVE CAPABILITY.  REDUNDANT PATHS REMAINING TO CONTINUE OPERATIONS: 1) OIRECT DRIVE 2) BACK-UP ORIVE 3) JETTISON (TO SECURE ORBITER)	EEE PARTS INSPECTION IS PERFORMED AS REQUIRED BY SPAR-RMS-PA.003. EACH EEE PART IS QUALIFIED AT THE PART LEVEL TO THE REQUIREMENTS OF THE APPLICABLE SPECIFICATION. ALL EEE PARTS ARE 1003 SCREEMED AND BURMED IN. AS A MINIMUM, AS REQUIRED BY SPAR-RMS-PA.003, BY THE SUPPLIER. ADDITIONALLY, EEE PARTS ARE 1003 RE-SCREEMED IN ACCORDANGE WITH REQUIREMENTS, BY AM INDEPENDENT SPAR APPROVED TESTING FACILITY. OPE 15 PERFORMED AS REQUIRED BY PA.003 ON A RANDOMLY SELECTED 5% OF PARTS, MAXIMUM 5 PIECES, MINIMUM 3 PIECES FOR EACH LOT NUMBER/DATE CODE OF PARTS RECEIVED.  WIRE 1S PROCURED TO SPECIFICATION MIL-W-22759 OR MIL-W-813B1 AND INSPECTED AND TESTED TO MASA JSCHOODO STANDARD MUMBER 95A.  RECEIVING IMSPECTION VERIFIES THAT ALL PARTS RECEIVED ARE AS IDENTIFIED IN THE PROCUREMENT DOCUMENTS, THAT HO PHYSICAL DANAGE HAS OCCURRED TO PARTS DURING SHIPMENT, THAT HE RECEIVING DOCUMENTS PROVIDE ADEQUATE TRACEABILITY INFORMATION AND SCREENING DATA CLEARLY IDENTIFIES ACCEPTABLE PARTS.  PARTS ARE IMSPECTED THROUGHOUT MANUFACTURE AND ASSEMBLY AS APPROPRIATE TO THE MANUFACTURING STAGE COMPLETED. THESE INSPECTIONS INCLUDE,  PRINTED CIRCUIT BOARD INSPECTION FOR TRACK SEPARATION, DAMAGE AND ADEQUACY OF PLATED THROUGH HOLES,  COMPONENT MOUNTING INSPECTION FOR CORRECT SOLDERING, MIRE LOOPING, STRAPPING, ETC. OPERATORS AND INSPECTORS ARE TRAINED AND CERTIFIED TO MASA MHB 5300.4(3A) STANDARD, AS MODIFIED BY JSC 08600A.  COMFORMAL COATING INSPECTION FOR ADEQUATE PROCESSING IS PERFORMED USING ULTRAVIOLET LIGHT TECHNIQUES.  POST P. C. BD. INSTALLATION INSPECTION, CHECK FOR CORRECT BOARD INSTALLATION, ALIGMENT OF BOARDS, PROPER CONNECTOR CONTACT MATHMG, MIRE ROUTING, STRAPPING OF MIRES ETC.  PRE-TEST INSPECTION OF DRC PANEL ASSY INCLUDES AN AUDIT OF LOWER TIEST DOCUMENTS, TEST EQUIPMENT CALIBRATION VERIFICATION TO AS DESIGN ETC. (SPAR/GOVERNMENT REP.  PRE-TEST INSPECTION POINT)  A TEST READINESS REVIEW (TRY WHICH INCLUDES VERIFICATION OF TEST PERSONNEL, TEST DOCUMENTS, TEST EQUIPMENT CALIBRATION VALIDATION STATUS AND MARDARDAR CONFIGURATION IS CO

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FMEA REF.	FMEA REV.	NAME, GTY, & DRAWING REF. DESIGNATION	FAILURE MODE AND CAUSE	FAILURE EFFECT ON END ITEM	HOUR / FUNC. RATIONALE FOR ACCEPTANCE 2/1R CRITICALITY SCREENS: A-PASS, B-PASS, C-PASS
1045	0	MCIU-DEC DATA INIERFACE GTY-1 SCHEMATIC ED B7305	MODE: CORRUPT DATA SENT TO DAC.  CAUSE(S): (1) INPUT SHIFT REGISTER OR LATCH MALFUNCTION FOR DATA ONLY.	LOSS OF COMMUNICATION WITH DAC INTERFACE WILL INITIATE DAC COMMUNICATION FAILURE DETECTION. AUTOBRAKES. ARM COMES TO REST. GPC GOES INTO IDLE MODE. LOSS OF COMPUTER SUPPORTED MODES. ABE COMMUNICATION PATH REMAINS OPENABLE. LOSS OF LIMPING DURING END EFFECTOR CAPTURE. WORST CASE UNABLE TO RELEASE BRAKES. LOSS OF ARM DRIVE CAPABILITY.  REDUNDANT PATHS REMAINING TO CONTINUE OPERATIONS: 1) DIRECT DRIVE 2) BACK-UP DRIVE 3) JETTISON (TO SECURE ORBITER)	THERMAL AND VIBRATION TESTING, (SPAR/GOVERNMENT REP. MANDATORY INSPECTION POINT).  INTEGRATION OF DAC PANEL, RHC, THC AND MCIU, INSPECTIONS ARE PERFORMED AT EACH STAGE OF INTEGRATION, WHICH INCLUDES CROWNDING CHECKS, INTER CONNECT CABLE VERTFICATION, CONNECTOR INSPECTION FOR BENT OR PUSHBACK CONTACTS ETC.  SUB-SYSTEM PERFORMANCE TESTING (ATP), INCLUDES AN AMBIENT PERFORMANCE TEST, (MANDATORY INSPECTION OF MECHANICAL ARM, SUBASSEMBLIES AND THE FLIGHT CABIN EQUIPMENT TO FORM THE SRMS. INSPECTIONS ARE PERFORMED AT EACH PHASE OF INTEGRATION WHICH INCLUDES GROUNDING CHECKS, THRU WIRING CHECKS, WHING ROUTING, INTERFACE CONNECTORS FOR BENT OR PUSH BACK CONTACTS ETC.  SRMS SYSTEMS TESTING - STRONGBACK AND FLAT FLOOR AMBIENT PERFORMANCE TEST. (SPAR/GOVERNMENT REP MANDATORY INSPECTION POINT)
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PREPARED BY	: <u>M</u>	FUG	SUPERCEDING DATE	: NONE	DATE: 11 JUL 91 CIL REV: 0

	TEMS LIST	AS	OJECT: <u>SAMS (-5 MC</u> S'Y NOMENCEATURE: <u>D</u>	C PANEL	SYSTEM: D&C SUBSYSTEM ASS'Y P/R: 51140E391	SHEET: _
THEA FHE	A HAME GTY, & DRAWING REF. DESIGNATION	FAILURE MODE AND CAUSE	FAILURE EFFECT ON FEND 1TEM	HDWR / FUNC. 2/1R CRITICALITY	RATIONALE FOR ACCEPTANCE SCREENS: A-PASS, B-PASS, C-PASS	
1045 0	MCIU-DEC DATA INTERFACE QTY-1 SCHEMATIC ED 87305	MODE: CORRUPT DATA SENT TO D&C. CAUSE(S): (1) EMPUT SHIFT REGISTER OR LATCH HALFUNCTION FOR DATA ONLY.	LDSS OF COMMUNICATION WITH DAC INTERFACE WILL INITIATE OBC COMMUNICATION FAILURE DETECTION, AUTOBRAKES, ARM COMES TO REST. GPC GOES INTO IDLE MODE. LOSS OF COMPUJER SUPPORTED MODES, ABE COMMUNICATION PATH REMAINS OPERABLE. LOSS OF LIMPING DURING END EFFECTIOR CAPTURE. WORST CASE UNABLE TO RELEASE BRAKES. LOSS OF ARM DRIVE CAPABILITY.  REDUNDANT PATHS REMAINING TO CONTINUE OPERATIONS: 1) DIRECT DRIVE 2) BACK-UP DRIVE 3) JETTISON (TO SECURE ORBITER)	FAILURE HISTO	ORY EEN NO FAILURES ASSOCIATED WITH THIS FAILURE	
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PROJECT: SRMS (-5 MCTU INSTALLED)
ASS'Y NOMENCLATURE: DEC PAREL

SYSTEM: DEC SUBSYSTEM ASS'Y P/A: 51140E391

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FMEA REF.	FMEA REV.	NAME GTY & DRAWING REF. DESIGNATION	FAILURE HODE AND CAUSE	FAILURE EFFECT ON END ITEM	HDWR / FUNC. RATIONALE FOR ACCEPTANCE 2/1R CRITICALITY SCREENS: A-PASS, B-PASS, C-PASS
1045	O.	MCIU-DEC DATA ENTERFACE OTY-1 SCHEMATIC ED 67305	MCDE: CORRUPT DATA SENT TO D&C.  CAUSE(S): (1) INPUT SHIFT REGISTER OR LATCH MALFUNCTION FOR DATA ONLY.	LOSS OF COMMUNICATION WITH D&C INTERFACE WILL INITIATE D&C COMMUNICATION FAILURE DEJECTION. AUTOBRAKES. ARM COMES IG REST. GPC GOES INTO IDLE MODE. LOSS OF COMPUTER SUPPORTED MODES. ABE COMMUNICATION PATH REMAINS OPERABLE. LOSS OF LIMPING DURING EMD EFFECTOR CAPTURE.  WORST CASE UMABLE TO RELEASE BRAKES. LOSS OF ARM DRIVE CAPABILITY.  REDUNDANT PATHS REMAINING TO CONTINUE OPERATIONS: 1) DIRECT DRIVE 2) BACK-UP DRIVE 3) JETTISON (TO SECURE ORBITER)	OPERATIONAL EFFECTS  COMPUTER SUPPORTED MODES CANNOT BE USED TO COMPLETE THE MISSION. DIRECT DRIVE AND BACKUP MODES REMAIN. IF PATLOAD AFFACUED, THE ARM SHOULD BE MANELIVERED TO A SAFE POSITION FOR PAYLOAD RELEASE. LOSS OF NEXT REDUNDANT PATH RESULTS IN BEING ONE FATURE AWAY FROM INABILITY TO CRADLE ARM. IF MITH SUBSEQUENT FAILURES ALL DRIVE MODES ARE LOST, THE ARM MAY BE JETTISONED.  CREW ACTION  USE DIRECT DRIVE  CREW TRAINING  HOME  OMRSD OFFLINE  VERIFY NO DEC/NCIU COMM FAILURES.  OMRSD OMLINE INSTALLATION  NOME  OMRSD ONLINE TURNAROUND  VERIFY NO DEC/MCIU COMM FAILURES.
EPARED BY		e WG	SUPERCEDING DATE		PAGE 54 OF 471